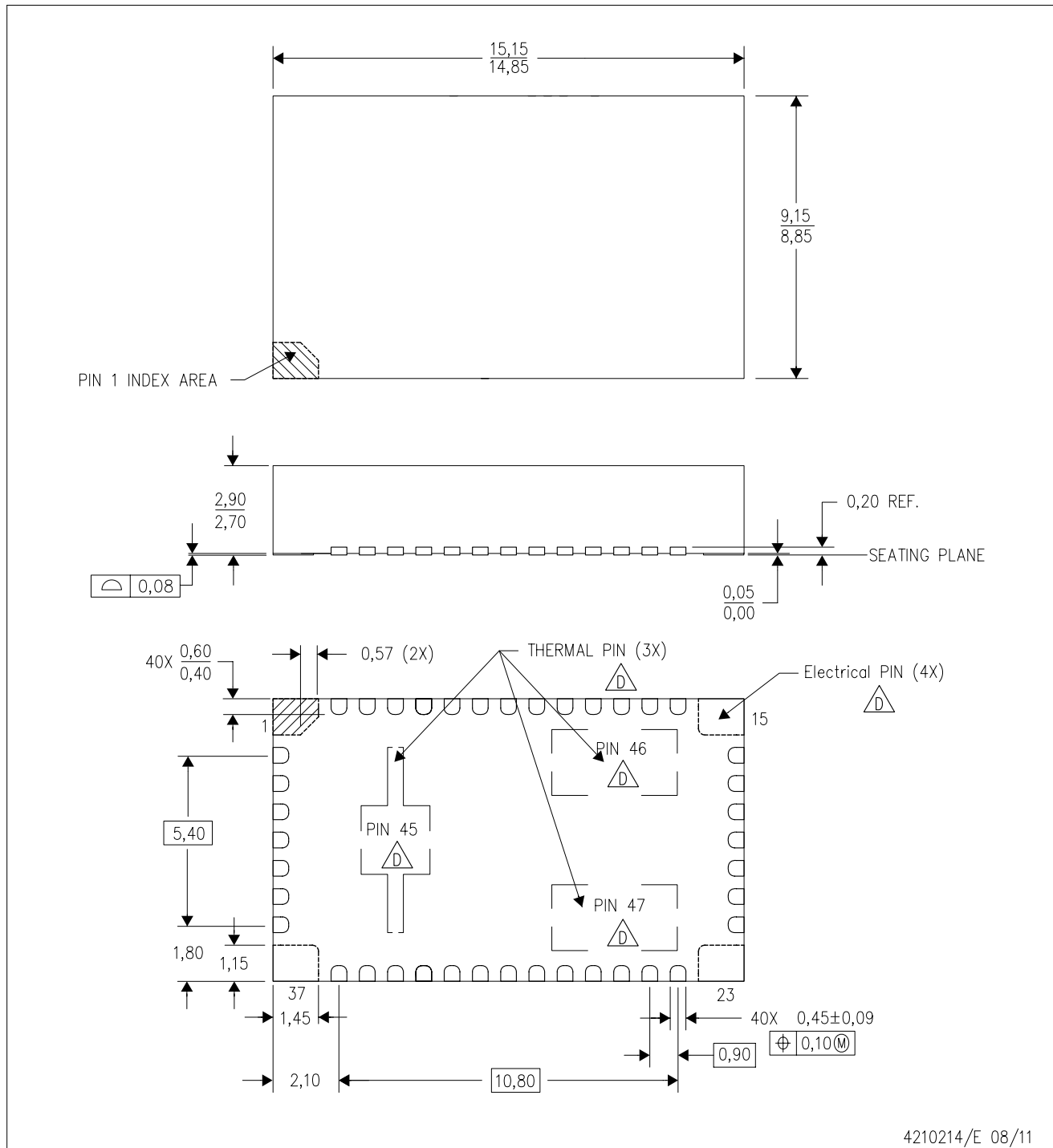




MECHANICAL DATA

RUQ (R-PB1QFN-N47)

PLASTIC QUAD FLATPACK NO-LEAD



4210214/E 08/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-leads (QFN) package configuration.
 -  The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 -  The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane.

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